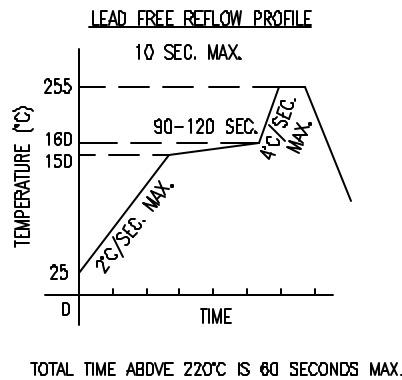
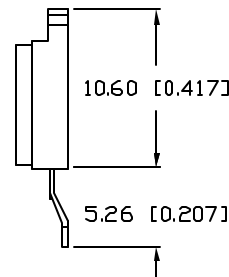
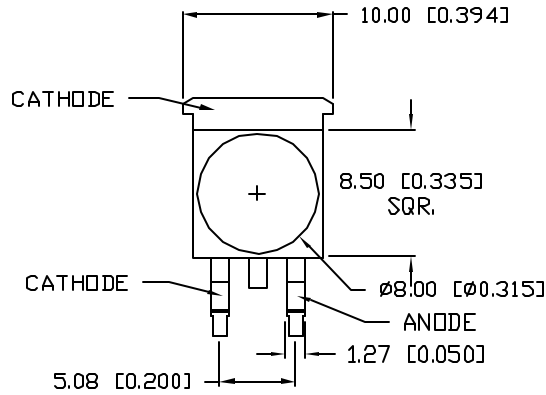
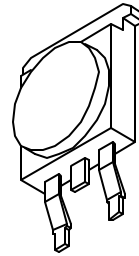
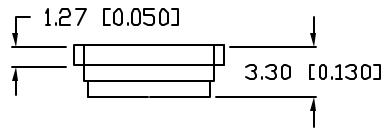
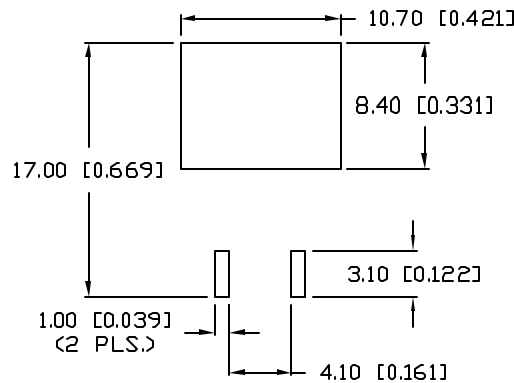


UNCONTROLLED DOCUMENT



SOLDER PAD LAYOUT



PART NUMBER
SML-LX1610UWC/A

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11388.	01.11.07

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=350\text{mA}$

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH					nm	
FORWARD VOLTAGE	V_f		3.5	4.0	V	$I_f=350\text{mA}$
REVERSE VOLTAGE	V_r	5			V	$I_f=10\mu\text{A}$
AXIAL INTENSITY(*1)	I_v		30		lm	$I_f=350\text{mA}$
COLOR TEMP.		3000		9000		$I_f=350\text{mA}$
VIEWING ANGLE			110		$2x \theta_{\text{half}}$	
EMITTED COLOR:		WHITE				
EPOXY LENS FINISH:		WATER CLEAR				

*1. AXIAL INTENSITY TESTING CONDITION: 550nm WAVELENGTH.
*2. THE ICI STANDARD COLORIMETRIC SYSTEM.

LIMITS OF SAFE OPERATION AT 25°C

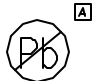
PARAMETER	SYMBOL	MAX	UNITS
PULSE FORWARD CURRENT	I_p	500	mA
STEADY CURRENT	I_F	350	mA
POWER DISSIPATION	P_D	1.5	W
OPERATING TEMP.	T_{OPR}	-20 TO +70	°C
STORAGE TEMP.	T_{STG}	-40 TO +85	°C

*DUTY 1/10 PULSE WIDTH 10ms

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.

NOTES:

1. 50 PCS. IN EACH TUBE.



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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

REV.	PART NUMBER
A	SML-LX1610UWC/A

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10.60 x 10mm HIGH POWER LED, ULTRA WHITE.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JC	CHECKED BY:	APPROVED BY:	DATE: 8.31.06
			PAGE: 1 OF 1
			SCALE: N/A